



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-01-02
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
------------------------------	------	----------------------------	----------

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD100N10F7	XMDP*OD0FR52	A	3068	2017-01-02
Amount	UoM	Unit type	ST ECOPACK Grade	
330.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 5th August 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.13	Die / Leadframe	400
Lead	6.13	Soft solder	18576

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	XMDP*0D0FR52									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	5.093	mg	supplier	die	Silicon (Si)	7440-21-3		4.881	mg	958382	14794				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.064	mg	12564	194				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	2356	36				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.073	mg	14331	221				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	589	9				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.040	mg	7852	121				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.003	mg	589	9				
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.017	mg	3337	52				
				Leadframe	Copper & its alloys	165.043	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	994601	497430
								supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1999	1000
supplier	alloy	Cobalt (Co)	7440-48-4						0.462	mg	2799	1400				
supplier	metallization	Nickel (Ni)	7440-02-0						0.092	mg	559	279				
supplier	metallization	Phosphorus (P)	12185-10-3						0.007	mg	42	21				
Soft solder	Solder	6.419	mg					JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.130	mg	954977	18576
				supplier	solder	Silver (Ag)	7440-22-4		0.161	mg	25082	488				
				supplier	solder	Tin (Sn)	7440-31-5		0.128	mg	19941	388				
				supplier	wire	Aluminium (Al)	7429-90-5		1.005	mg	996036	3045				
Encapsulation	Other Organic Materials	151.391	mg	supplier	mold compound	Magnesium (Mg)	7429-95-4		0.004	mg	3964	12				
				supplier	mold compound	Silica, vitreous	60676-86-0		132.466	mg	874993	401412				
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bi	EC 413-900-7		6.056	mg	40002	18352				
				supplier	mold compound	Epoxy Resin	25068-38-6		4.542	mg	30002	13764				
				supplier	mold compound	phenol resin	29690-82-2		7.570	mg	50003	22939				
Connections coating	Solder	1.045	mg	supplier	mold compound	Carbon black	1333-86-4		0.757	mg	5000	2294				
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167				